MAXPLAS

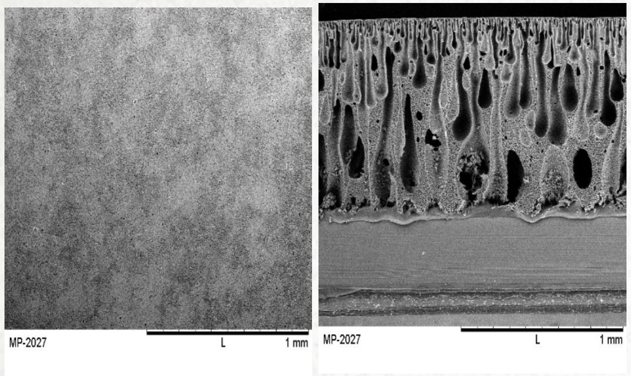
POLISHING PAD OF DUKSUNG

DUKSUNG CO.,LTD

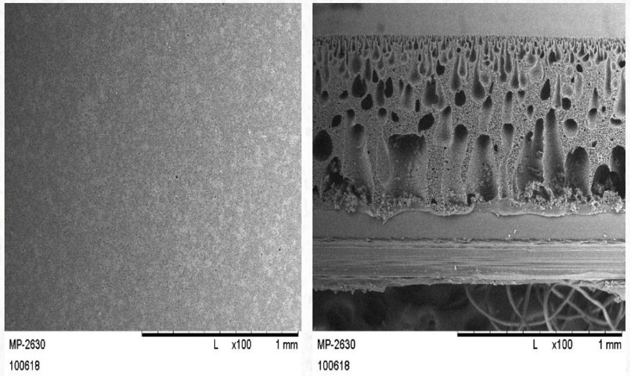
■ LCD Back pad

Developed to hold LCD glass substrates without wax. Users are able to gain highest level of flatness.

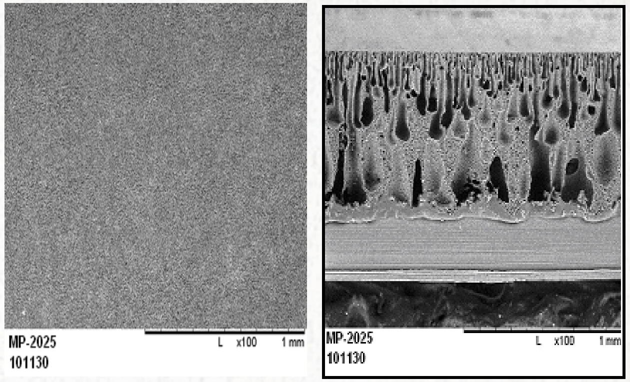
MP-2027



MP-2025NB



MP-2025B/F

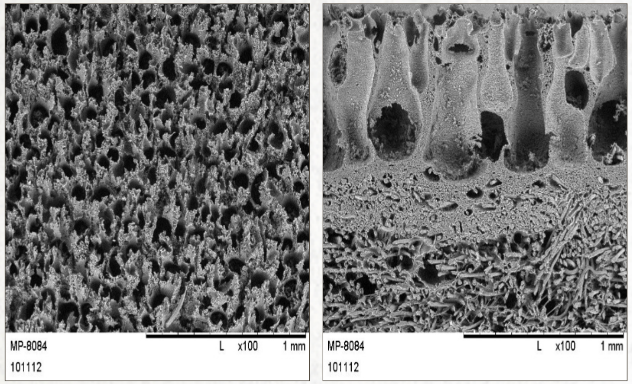


ITEM	MP-2027	MP-2025NB	MP-2025 B/F
Thickness(mm)	1.00	1.00	1.00
Density(g/cm3)	0.49	0.49	0.5
Compressibility(%)	38.5	37.5	37.3
Elasticity(%)	92.1	93.8	80.6
Hardness(Asker C)	67.0	67.5	68.0

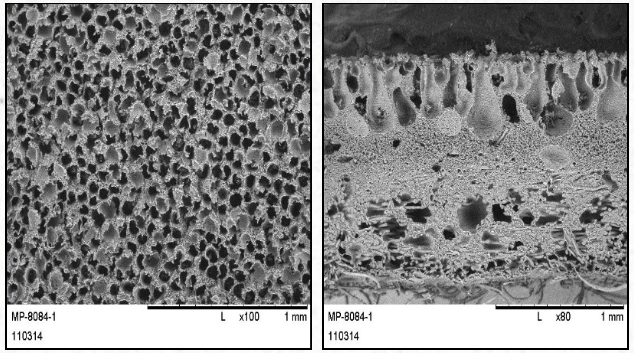
■ Suede types – Final polishing pad

Polishing pads for final polishing of wafers, glass and hard-disks. High precision on finished surfaces and perfect flatness are achieved.

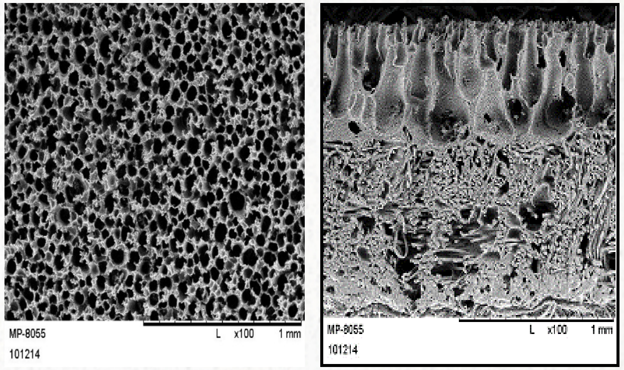
MP-8084



MP-8084-1



MP-8055

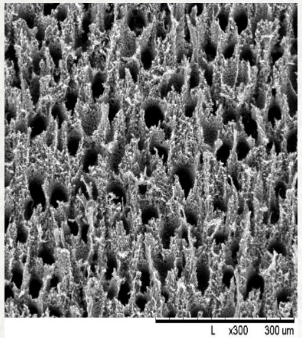


ITEM	MP-8084	MP-8084-1	MP-8055
Thickness(mm)	1.40	1.40	1.40
Density(g/cm3)	0.41	0.40	0.39
Compressibility(%)	10.1	10.3	11.2
Elasticity(%)	88.3	79.4	88.0
Hardness(Asker C)	69.0	72.0	68.0
Pore size(um)	68.2	63.5	67.

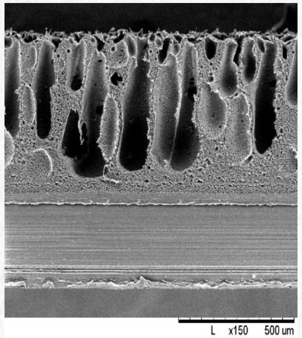
■ Suede type – Hard disk polishing pad

Polishing pads for final polishing of wafers, glass and hard-disks. High precision on finished surfaces and perfect flatness are achieved.

MP-2106



Maxplas-2106(PU=0.60 50µmBuff)



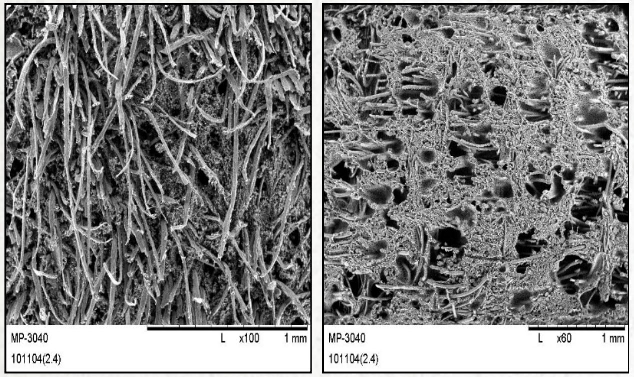
Maxplas-2106(PU=0.60 50µmBuff)

ITEM	MP-2106
Thickness(mm)	0.70
Density(g/cm3)	0.62
Compressibility(%)	4.5
Elasticity(%)	84.8
Hardness(Asker C)	83.0
Pore size(um)	35.6

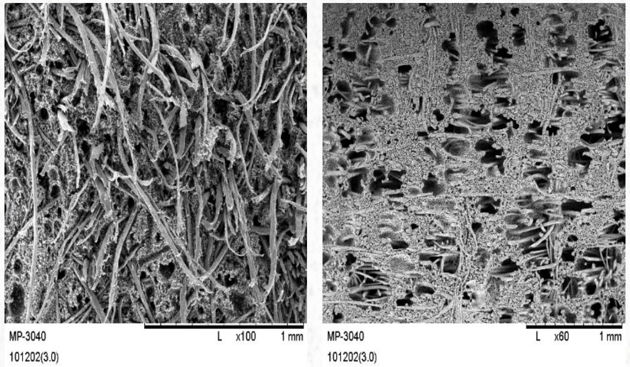
■ Edge polishing pad

Developed for edge polishing of wafers.

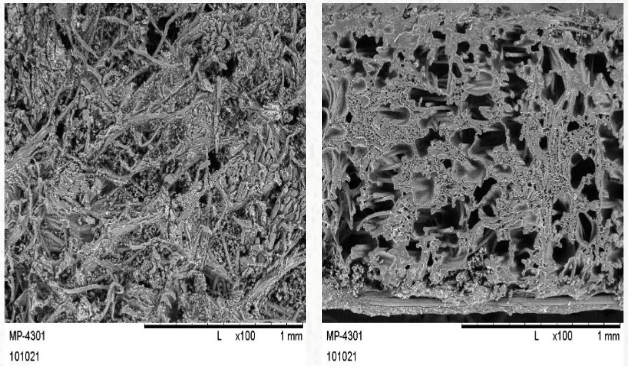
MP-3040(2.4)



MP-3040(3.0)



MP-3030

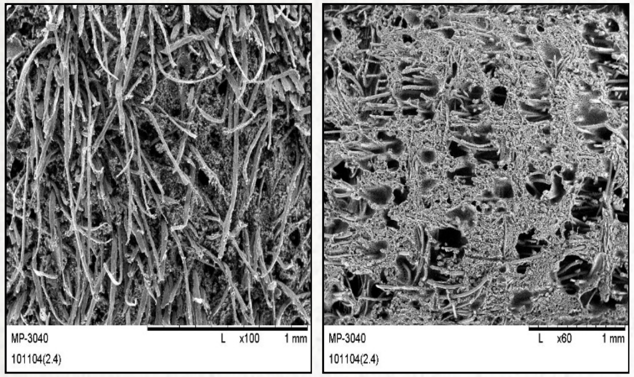


ITEM	MP-3040(2.4)	MP-3040(3.0)	MP-3030
Thickness(mm)	2.4	3.0	1.3
Density(g/cm3)	0.33	0.33	0.31
Compressibility(%)	4.9	4.1	9.3
Elasticity(%)	84.9	85.4	86.6
Hardness(Asker C)	77.2	77.5	72.5

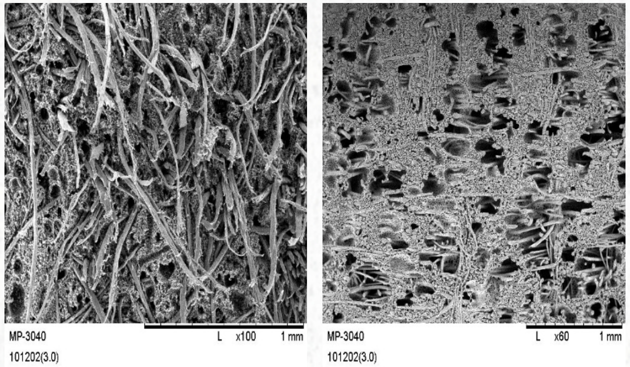
■ Notch polishing pad

Developed for notch polishing of wafers.

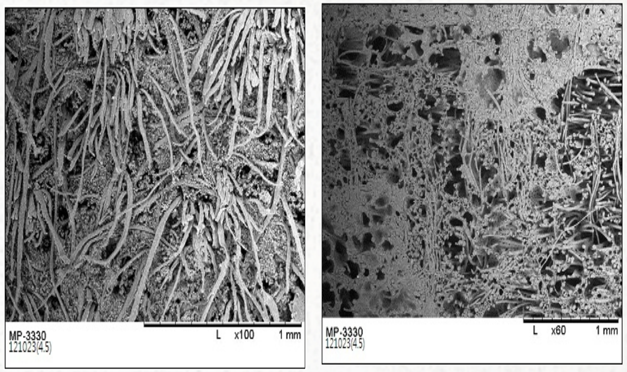
MP-3340(4.0)



MP-3340(4.5)



MP-3330(4.5)

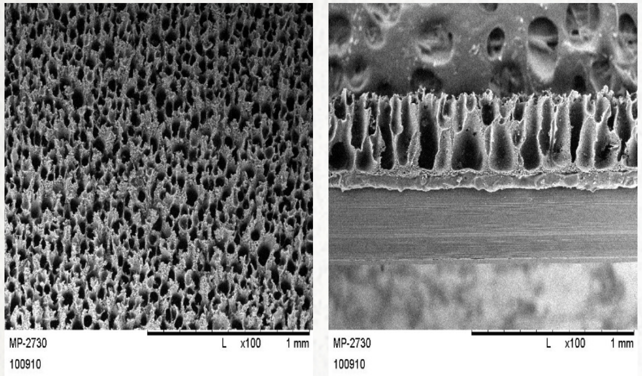


ITEM	MP-3340(4.0)	MP-3340(4.5)	MP-3330(4.5)
Thickness(mm)	4.0	4.5	4.5
Density(g/cm3)	0.46	0.44	0.41
Compressibility(%)	4.6	3.1	4.2
Elasticity(%)	83.7	83.2	91.4
Hardness(Asker C)	84.0	86.0	83.0

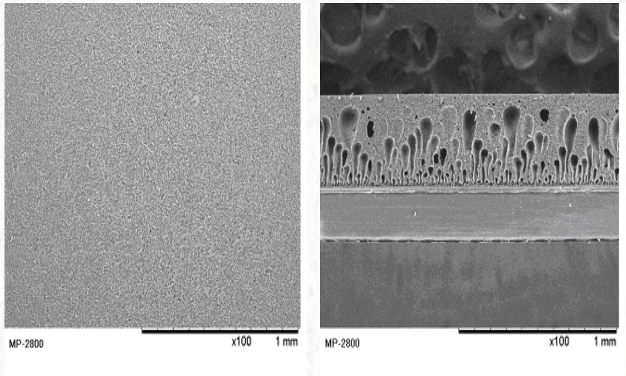
■ Back pad

For CMP & Template mounting pads. A film type without a frame and a template type with a frame are available.

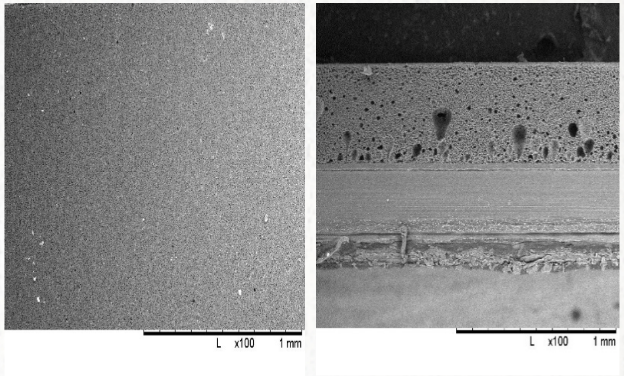
MP-2730



MP-2800



MP-2520NB

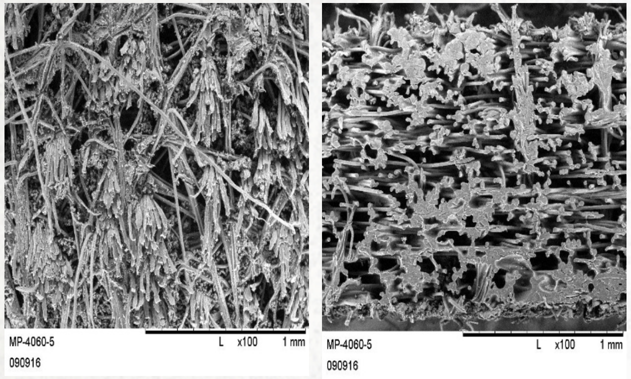


ITEM	MP-2730	MP-2800	MP-2520NB
Thickness(mm)	0.6	0.6	0.7
Density(g/cm3)	0.62	0.68	0.69
Compressibility(%)	15.3	4.8	6.7
Elasticity(%)	92.0	88.7	82.6
Hardness(Asker C)	77.0	80.0	77.5
Pore size(um)	41.9	-	-

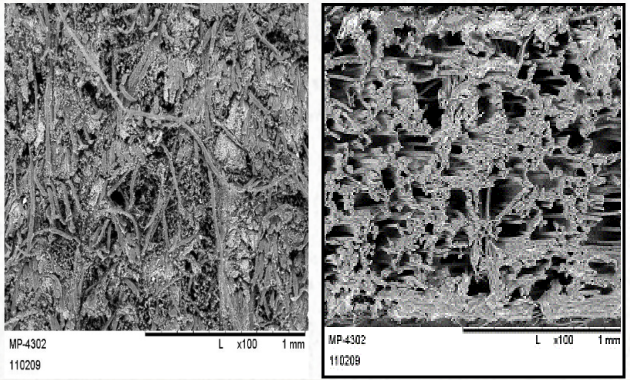
■ Wafering pad – Stock removal polishing pad

Developed for stock removal polishing of wafers.

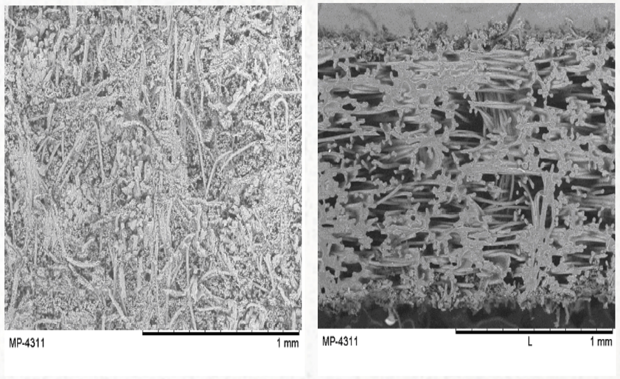
MP-4060



MP-4302



MP-4311

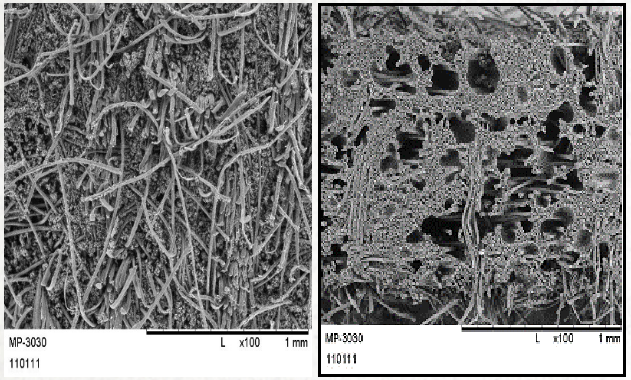


ITEM	MP-4060	MP-4302	MP-4311
Thickness(mm)	1.3	1.3	1.3
Density(g/cm3)	0.38	0.48	0.49
Compressibility(%)	5.3	4.3	6.2
Elasticity(%)	74.5	80.3	74.3
Hardness(Asker C)	87.7	88.0	83.6

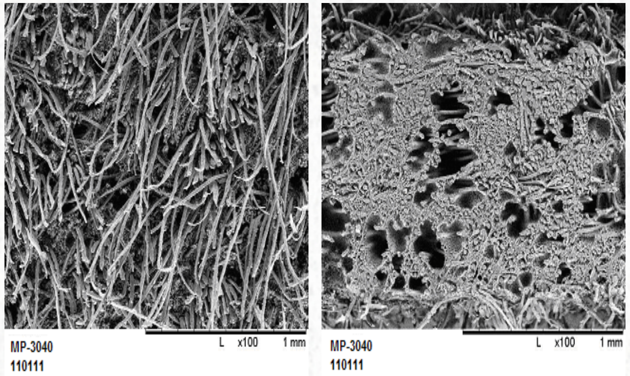
■ Wafering pad – Back polishing pad

Developed for back polishing of wafers.

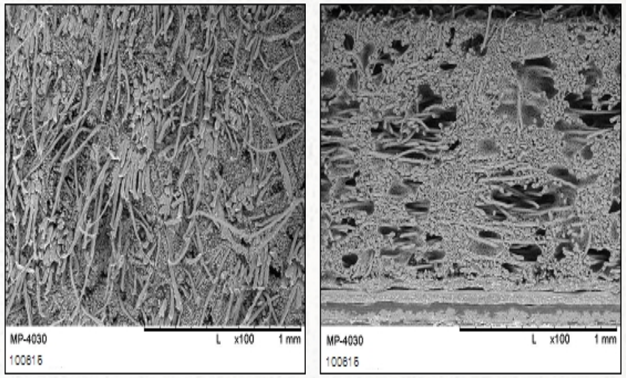
MP-3030



MP-3040



MP-4030



ITEM	MP-3030	MP-3040	MP-4030
Thickness(mm)	1.3	1.3	1.3
Density(g/cm3)	0.31	0.33	0.31
Compressibility(%)	9.3	9.3	9.5
Elasticity(%)	86.6	83.3	85.7
Hardness(Asker C)	72.5	74.5	68.5

■ Customer

Application	Item	User
Stock Polishing Pad	MP-4060 MP-4312	Kunsan Sino, ST&A, Worldex, SK Solmix
Edge Polishing Pad	MP-3030 MP-3040 MP-3340	LG Siltron, MEMC, SUMCO, Shinetsu, Siltronics AG
Notch Polishing Pad	MP-3340 MP-3330	LG Siltron, MEMC, SUMCO, Shinetsu, Siltronics AG
Final Polishing Pad	MP-8084 MP-8055	Nanos, LG Innotek
Glass Holder Pad	MP-2025	ITA Glass, Photo Jet, Bai De, G-Tech
Back Polishing Pad	MP-4030 MP-3030	Steco, Amkor, Fairchild, LB Semicon
Chuck Pad	MP-2800 MP-2580	LG Siltron, MEMC, SUMCO, Shinetsu
Back Pad	MP-2730	ST&A, Lentsu

■ Strength of Company and Product

Products which perfectly fit your uses

PU resins for Polishing pads are produced in-house
Physical properties and Construction of Products can be customized according to your special request

Technology and Know-how

Strengthening our production and R&D system to keep up with advancing polishing technologies

Business activity doing with global customers

Accumulated credibility through supplying products to global leader customers in I T industry

ISO9001, ISO14001 Certified

We promise to establish a quality assurance system to make continuous improvements